

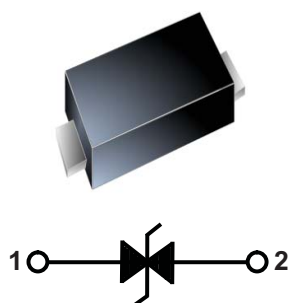
## Features

- 60W Peak Pulse Power Per Line(8/20us)
- 3.3V Working Peak Reverse Voltage
- Maximum Reverse Peak Pulse Current:4.5A
- ESD per IEC 61000-4-2(Contact):25KV
- ESD per IEC 61000-4-2(Air):30KV
- Clamping Voltage @IPP=1A:6V
- Junction Capacitance:10PF
- Package:SOD-523(0603)
- Polarity: Bidirectional

## Mechanical Characteristics

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- Lead Finish: NiPdAu
- Case Material: “ Green ” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

## Schematic And Configuration



## Ordering Information

| Part Number   | Packaging   | Reel Size |
|---------------|-------------|-----------|
| TEVC10R0V3B1X | Tape & Reel | 7inch     |

## Absolute Maximum Ratings (Ta=25°C,RH=45%-75%,unless otherwise noted)

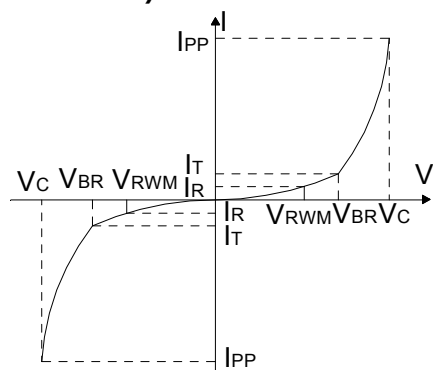
| Parameter                   | Symbol | Value    | Unit |
|-----------------------------|--------|----------|------|
| Operating Temperature Range | Tj     | -55~+125 | °C   |
| Storage Temperature Range   | Tstg   | -55~+150 | °C   |

## Electrical Characteristics (Ta=25°C)

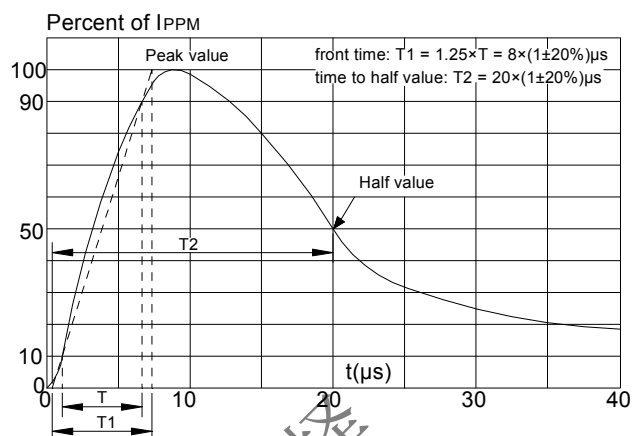
| Parameter               | Symbol | Min | Type | Max | Unit | Test Condition       |
|-------------------------|--------|-----|------|-----|------|----------------------|
| Reverse Working Voltage | Vrwm   |     |      | 3.3 | V    |                      |
| Breakdown Voltage       | Vbr    | 4   |      |     | V    | It=1mA               |
| Reverse Leakage Current | Ir     |     |      | 1   | uA   | Vrwm=3.3V            |
| Clamping Voltage        | Vc     |     | 6    | 8   | V    | Ipp=1A(8×20us pulse) |
| Juntion Capacitance     | Cj     |     | 9.5  | 15  | pF   | Vr=0V,f=1MHz         |

# Typical Performance Characteristics (Ta=25°C, unless otherwise noted)

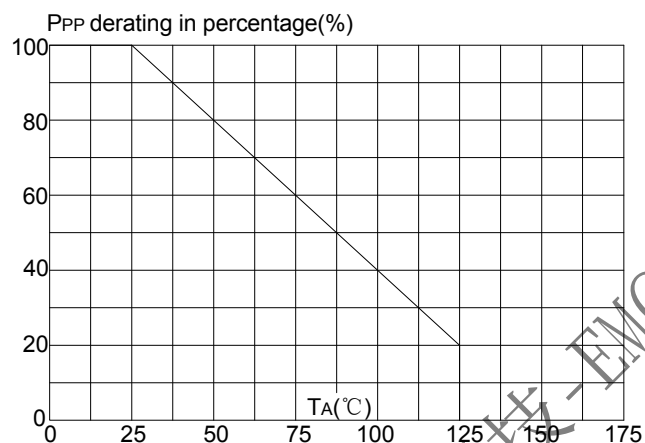
## V- I curve characteristics (Bi-directional)



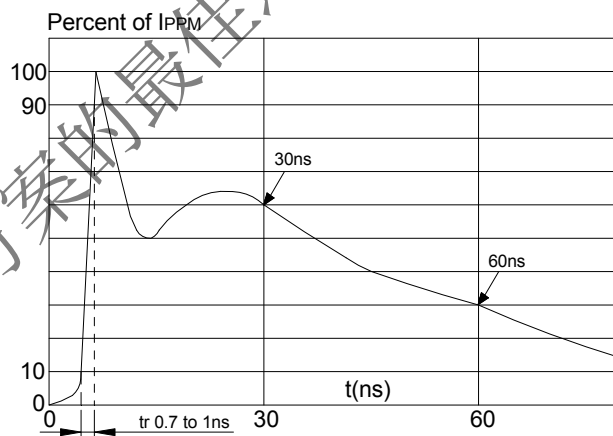
## Pulse waveform (8/20μs)



## Pulse derating curve

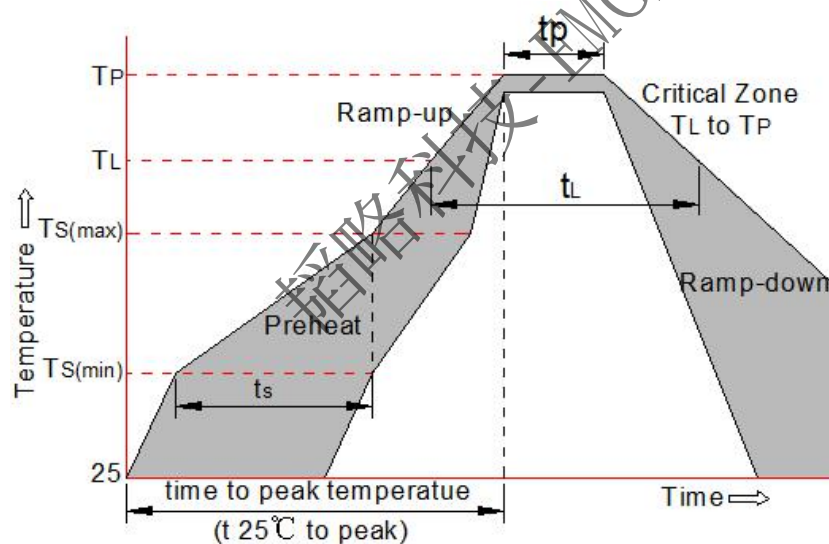


## ESD clamping (30kV contact)

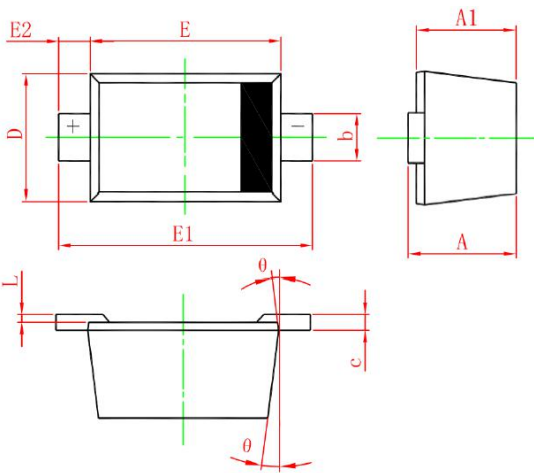


## Soldering Parameters

| Reflow Condition                                        |                                   | Pb-Free Assembly<br>(see as bellow) |
|---------------------------------------------------------|-----------------------------------|-------------------------------------|
| Pre Heat                                                | -Temperature Min ( $T_{s(min)}$ ) | +150°C                              |
|                                                         | -Temperature Max( $T_{s(max)}$ )  | +200°C                              |
|                                                         | -Time (Min to Max) ( $t_s$ )      | 60-180 secs.                        |
| Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak) |                                   | 3°C/sec. Max                        |
| $T_{s(max)}$ to $T_L$ - Ramp-up Rate                    |                                   | 3°C/sec. Max                        |
| Reflow                                                  | -Temperature( $T_L$ ) (Liquid us) | +217°C                              |
|                                                         | -Temperature( $t_L$ )             | 60-150 secs.                        |
| Peak Temp ( $T_P$ )                                     |                                   | +260(+0/-5)°C                       |
| Time within 5°C of actual Peak Temp ( $t_p$ )           |                                   | 30 secs. Max                        |
| Ramp-down Rate                                          |                                   | 6°C/sec. Max                        |
| Time 25°C to Peak Temp ( $T_P$ )                        |                                   | 8 min. Max                          |
| Do not exceed                                           |                                   | +260°C                              |

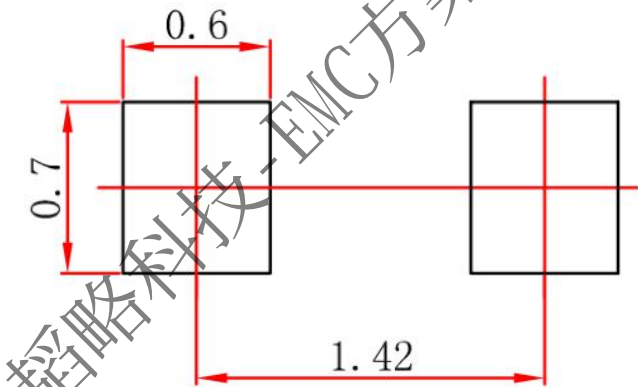


Package Mechanical Data



| SYM | DIMENSIONS  |     |      |          |     |       |
|-----|-------------|-----|------|----------|-----|-------|
|     | MILLIMETERS |     |      | INCHES   |     |       |
|     | MIN         | NOM | MAX  | MIN      | NOM | MAX   |
| A   | 0.51        | -   | 0.77 | 0.020    | -   | 0.031 |
| A1  | 0.50        | -   | 0.70 | 0.020    | -   | 0.028 |
| b   | 0.25        | -   | 0.35 | 0.010    | -   | 0.014 |
| c   | 0.08        | -   | 0.15 | 0.003    | -   | 0.006 |
| D   | 0.75        | -   | 0.85 | 0.030    | -   | 0.033 |
| E   | 1.10        | -   | 1.30 | 0.043    | -   | 0.051 |
| E1  | 1.50        | -   | 1.70 | 0.059    | -   | 0.067 |
| E2  | 0.20REF     |     |      | 0.008REF |     |       |
| L   | 0.01        | -   | 0.07 | 0.001    | -   | 0.003 |
| Φ   | 7° REF      |     |      | 7° REF   |     |       |

Suggested Land Pattern



Contact Information

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